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IN THE SPECIFICATION

Please amend the paragraph on page 11, line 17, as follows:

Figure 6D illustrates a subsequent processing stage where a top metal layer 612 is deposited above the inter-metal dielectric layer 610 in electrical communication with the interconnect vias 606. Note, for example, operation 508 of the method 500 of Figure 5. Such top metal layer 612 thus serves as the bond pad.